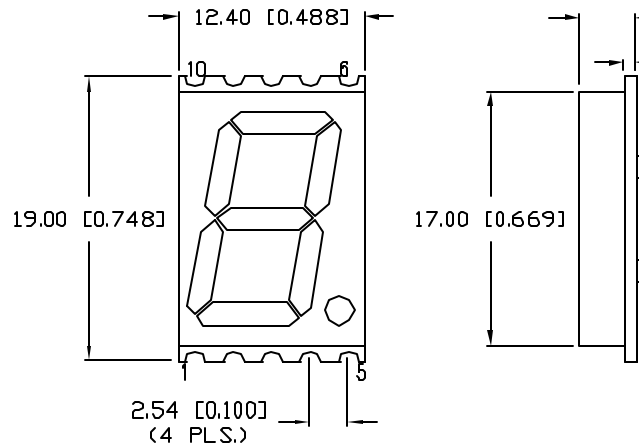
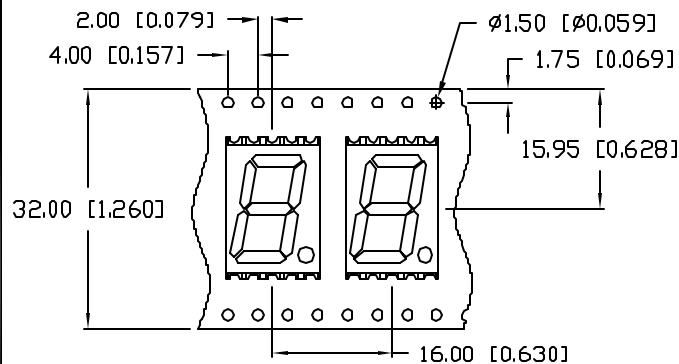
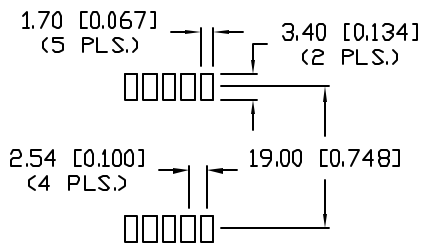


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RECOMMENDED SOLDER PAD LAYOUT



TAPE FEED DIRECTION →

*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X=±1 (±0.039), X.X=±0.5 (±0.020), X.XX=±0.25 (±0.010), X.XXX=±0.127 (±0.005). LEAD SIZE=±0.05 (±0.002), LEAD LENGTH=±0.75 (±0.030). MIN.=^{+0.00}_{-0.00} DECIMAL PRECISION MAX.=^{+0.00}_{-0.00} DECIMAL PRECISION

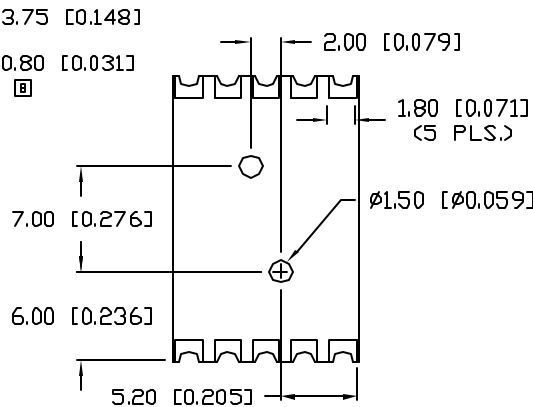
REV.

B

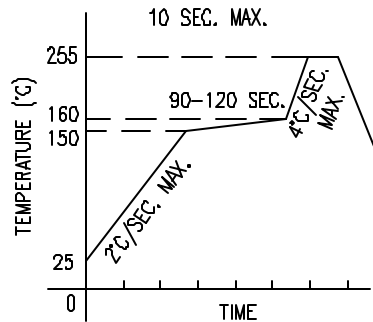
PART NUMBER

LDS-SMA5612RISUGTR

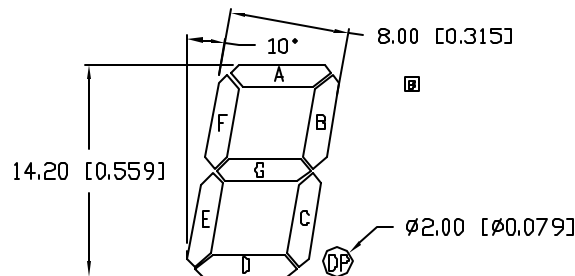
0.56" SINGLE DIGIT SEVEN SEGMENT SMT DISPLAY,
SURFACE MOUNT, 574nm GREEN CHIPS,
GRAY FACE, MILKY WHITE DIFFUSED.



LEAD FREE REFLOW PROFILE



TOTAL TIME ABOVE 220°C IS 60 SECONDS MAX.

PART NUMBER
LDS-SMA5612RISUGTR

REV.

B

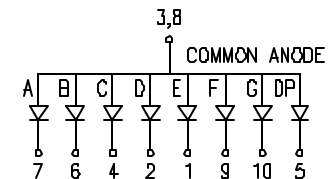
REV.	E.C.N. NUMBER AND REVISION COMMENTS	DATE
A	E.C.N. #11204 & 11205.	12.28.04
B	E.C.N. #11420.	6.08.07

ELECTRO-OPTICAL CHARACTERISTICS $T_A=25^\circ\text{C}$ $I_f=10\text{mA}$

PARAMETER	MIN	TYP	MAX	UNITS	TEST COND
PEAK WAVELENGTH		574		nm	
FORWARD VOLTAGE		2.2	2.6	V_f	
REVERSE VOLTAGE	5.0			V_r	$I_r=100\mu\text{A}$
AXIAL INTENSITY		7000		μcd	$I_f=10\text{mA}$
EMITTED COLOR:	GREEN				
FACE COLOR:	GRAY				
SEGMENT COLOR:	MILKY WHITE DIFFUSED				

LIMITS OF SAFE OPERATION AT 25°C PER CHIP

PARAMETER	MAX	UNITS
PEAK FORWARD CURRENT*	150	mA
STEADY CURRENT	25	mA
POWER DISSIPATION	105	mW
DERATE FROM 25°C	-1.2	mW/°C
OPERATING, STORAGE TEMP.	-40 TO +85	°C

* $t < 10\mu\text{s}$ 

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290 E. HELEN ROAD
PALATINE, IL 60067-6976
PHONE: +1.847.359.2790
US WEB: www.lumex.com
TW WEB: www.lumex.com.tw

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JN			9.4.03
			PAGE: 1 OF 1
			SCALE: N/A

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RELIABILITY NOTE

OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.